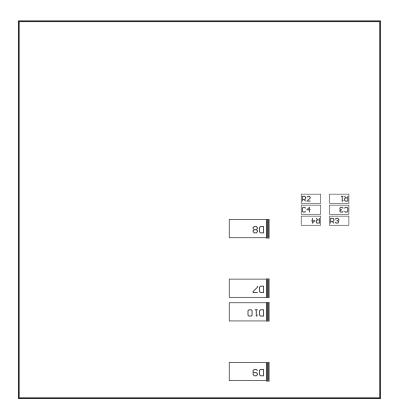


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP10812	REV: A	SVN REV	: Not In VersionControl
PLOT NAME = Top Assembly Drawing	GENERATED : 11/20/	2014 2:01:40	PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP10812	REV: A	SVN REV	: Not In VersionControl
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/20/	2014 2:01:41	PM	TEXAS INSTRUMENTS

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